

MS88SF3

Bluetooth Low Energy module

Specification V1.0

Small-sized nRF52833 Module MS88SF3 Specification



MS88SF3 is advanced, compact (23.2mm×17.4mm×2mm), highly flexible, ultra-low power wireless BLE 5.0 Module based on nRF52833 SoCs. Its powerful 32-bit ARM Cortex-M4 CPU, a 512KB flash memory, a 128KB RAM and integrating a 2.4 GHz transceiver offers the perfect solution for Bluetooth connectivity.

Features

1. ARM® Cortex® -M4 32-bit processor with FPU, 64 MHz
2. BLE 5 data rate: 2Mbps, 1Mbps, 500 kbps, 125kbps. IEEE 802.15.4 Thread and Zigbee data rate: 250kbps, Proprietary
- 2.4 GHz: 2 Mbps, 1 Mbps
3. Flash/RAM: 512kB/128kB
4. GPIO: 42
5. 2×UART/4×SPI masters/3×SPI slaves
6. SoC TX power: -40dB to +8dB
7. Operating temperature: -40°C to +105°C
8. Antenna: PCB
9. Module size: 18.5mm×12.5mm×2.0mm
10. Range: 125kbps: up to 250 meters in open space.

Application

1. Medical devices
2. Heart rate monitor
3. Blood pressure monitor
4. Blood glucose meter
5. Thermometer
6. Sport facilities
7. Weighing machine
8. Sports and fitness sensors
9. Accessories
10. 3D glasses and gaming controller
11. Mobile accessories
12. Remote controllers / Toys
13. Electronic devices
14. Cycle computer

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1 Product Introduction

MS88SF3 series are advanced, compact (18.5mm×12.5mm×2.0mm), highly flexible, ultra-low power wireless BLE 5.1 Module based on nRF52833 SoCs. Its powerful 32-bit ARM Cortex™ M4 with FPU, a 512KB flash memory, a 128KB RAM and integrating a 2.4 GHz transceiver can offers the perfect solution for Bluetooth connectivity.

Fully qualified BLE stacks for nRF52833 are implemented in the S140 Soft Devices which can be freely downloaded. In the meantime, ANT, ZIGBEE and THREAD applications can be supported by nRF52833 with extensive software.

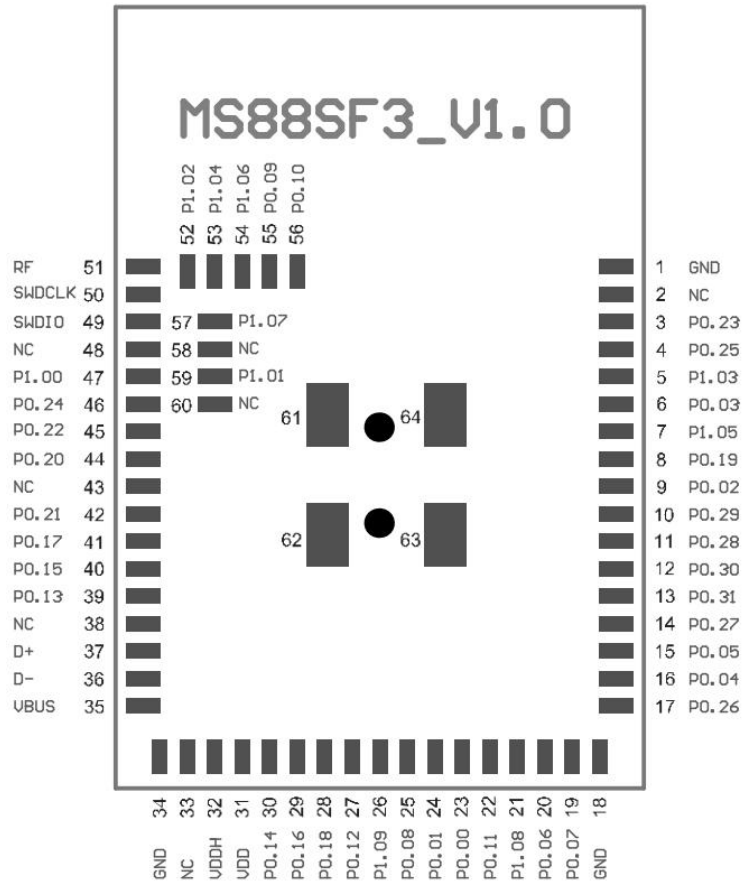
MS88SF3 can meet the most demanding applications, it allow faster time to market with high performance, low power management and reduced development cost. Also, its range is estimated up to 250 meters in open space for 1Mbps data rate; up to 120 meters in open space for 2 Mbps data rate.

1.1 Ordering information

Ordering number	Description
MS88SF3-1Y33AIR	nRF52833-QIAA BT 5.1 Module, PCB Antenna, Reel pack

2 Pin Description

2.1 Pin assignment



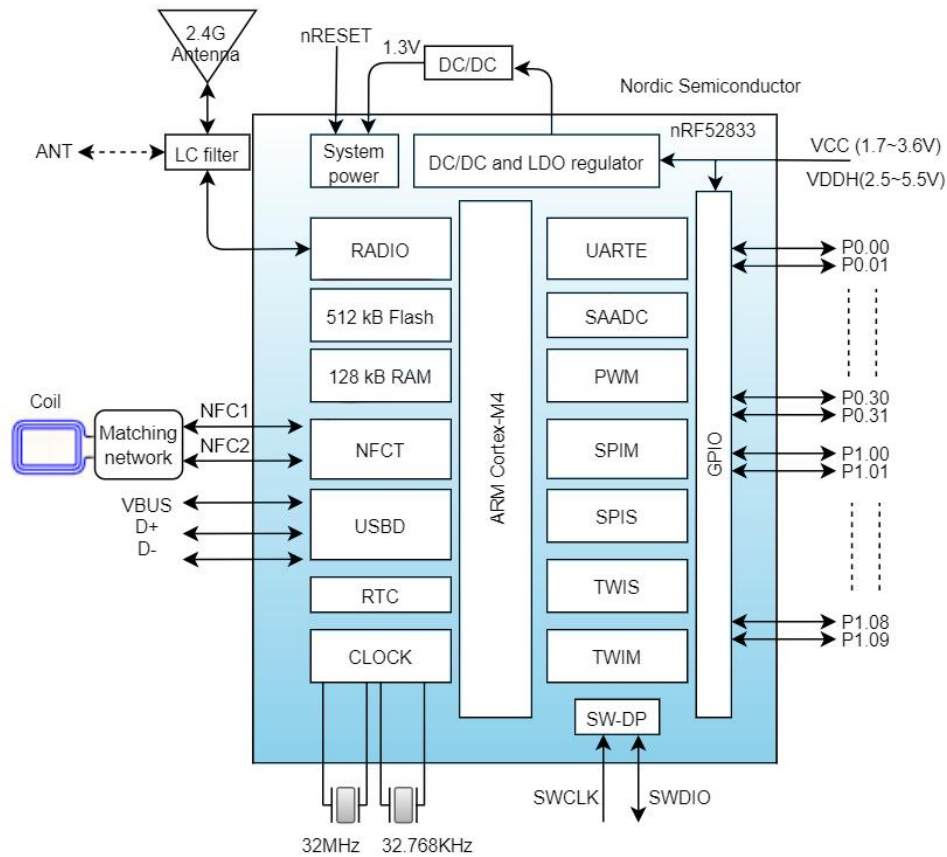
2.2 Pin definition

Symbol	Type	Description
VDD	Power	Power supply, 1.7V-3.6V
VDDH	Power	Power supply, 2.5V-5.5V
VBUS	Power	USB Power Supply, 4.35V-5.5V
D+	Digital I/O	USB D+
D-	Digital I/O	USB D-
GND	Power	Ground
SWDIO	Digital I/O	Hardware debug and flash/programming I/O
SWCLK	Digital input (debug)	Hardware debug and flash programming I/O
P 0.31 AIN7	Digital I/O	General purpose I/O
	Analog input	Analog input
P 0.29 AIN5	Digital I/O	General purpose I/O
	Analog input	Analog input
P 0.02 AIN0	Digital I/O	General purpose I/O
	Analog input	Analog input
P0.19	Digital I/O	General purpose I/O
P1.05	Digital I/O	General purpose I/O
P0.25	Digital I/O	General purpose I/O
P0.30 AIN6	Digital I/O	General purpose I/O
	Analog input	Analog input
P0.28 AIN4	Digital I/O	General purpose I/O
	Analog input	Analog input
P0.03 AIN1	Digital I/O	General purpose I/O
	Analog input	Analog input

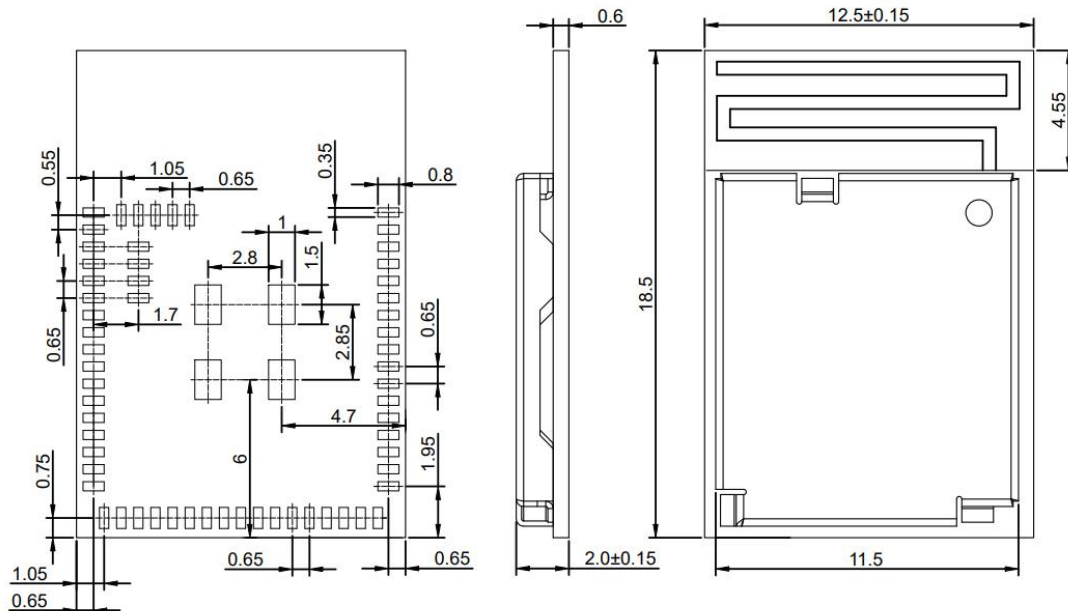
P1.03	Digital I/O	General purpose I/O
P0.23	Digital I/O	General purpose I/O
P0.00 XL1	Digital I/O Analog input	General purpose I/O Connection for 32.768 kHz crystal
P0.01 XL2	Digital I/O Analog input	General purpose I/O Connection for 32.768 kHz crystal
P0.26	Digital I/O	General purpose I/O
P0.27	Digital I/O	General purpose I/O
P0.04 AIN2	Digital I/O Analog input	General purpose I/O Analog input
P0.10	Digital I/O	General purpose I/O
NFC2	NFC input	NFC antenna connection
P0.05	Digital I/O	General purpose I/O
AIN3	Analog input	Analog input
P0.06	Digital I/O	General purpose I/O
P0.09 NFC1	Digital I/O NFC input	General purpose I/O NFC antenna connection
P0.07 TRACECLK	Digital I/O Trace clock	General purpose I/O Trace buffer clock
P0.08	Digital I/O	General purpose I/O
P1.08	Digital I/O	General purpose I/O
P1.07	Digital I/O	General purpose I/O
P1.09 TRACEDATA3	Digital I/O Trace data	General purpose I/O Trace buffer TRACEDATA[3]
P1.06	Digital I/O	General purpose I/O
P0.11 TRACEDATA2	Digital I/O	General purpose I/O

	Trace data	Trace buffer TRACEDATA[2]
P0.12 TRACEDATA1	Digital I/O	General purpose I/O
	Trace data	Trace buffer TRACEDATA[1]
P1.04	Digital I/O	General purpose I/O
P1.02	Digital I/O	General purpose I/O
P1.01	Digital I/O	General purpose I/O
P0.14	Digital I/O	General purpose I/O
P0.16	Digital I/O	General purpose I/O
P0.18 nRESET	Digital I/O	General purpose I/O Configurable as pin RESET
P0.21	Digital I/O	General purpose I/O
P0.13	Digital I/O	General purpose I/O
P0.15	Digital I/O	General purpose I/O
P0.17	Digital I/O	General purpose I/O
P0.20	Digital I/O	General purpose I/O
P0.22	Digital I/O	General purpose I/O
P0.24	Digital I/O	General purpose I/O
	Digital I/O	General purpose I/O
P1.00 TRACEDATA0	Trace data	Trace buffer TRACEDATA[0] Serial wire output (SWO)

2.3 Block diagram



2.4 Mechanical Drawing



Important: Unit: mm Tolerance: +/- 0.1, default
Recommend solder pad size: 1.1*0.35mm, Center GND pad: 1.8*1.3mm.

3 Electrical Specification

The electrical specifications of the module are directly related to the Nordic semiconductor Specifications for the nRF52833 chipset. The below information is only the extract from nRF52833 specification. For more detailed information, please refer to the up-to-date specification of the chipset available on the Nordic semiconductor website.

3.1 Absolute maximum ratings

	Note	Min.	Max	Unit
Supply voltages				
VDD		-0.3	+3.9	V
VDDH		-0.3	+5.8	V
VBUS		-0.3	+5.8	V
VSS			0	V
I/O Pin voltage				
$V_{I/O}, VDD \leq 3.6V$		-0.3	$VDD + 0.3V$	V
$V_{I/O}, VDD > 3.6V$		-0.3	3.9V	V
NFC antenna pin current				
$I_{NFC1/2}$			80	mA
Environmental (AQFN package)				
Storage temperature		-40	+125	°C
MSL	Moisture Sensitivity Level		2	
ESD HBM	Human Body Model		4	kV
ESD HBM Class	Human Body Model Class		3A	
ESD CDM	Charged Device Model		750	V
Flash Memory				
Endurance		10 000		write/erase cycles
Retention at 85 °C		10		years

Retention at 105 °C	Limited to 1000 write/erase cycles	3	years
Retention at 105 °C-85 °C, execution split	Limited to 1000 write/erase cycles	6.7	years

Important: Maximum ratings are the extreme limits to which the chip can be exposed for a limited amount of time without permanently damaging it. Exposure to absolute maximum ratings for prolonged periods of time may affect the reliability of the device.

3.2 Recommended operating conditions

The operating conditions are the physical parameters that the chip can operate within.

Symbol	Parameter	Min.	Nom.	Max.	Units
VDD	VDD supply voltage, independent of DCDC enable	1.7	3.0	3.6	V
VDD _{POR}	VDD supply voltage needed during power-on reset	1.75			V
VDDH	VDDH supply voltage, independent of DCDC enable	2.5	3.7	5.5	V
VBUS	VBUS USB supply voltage	4.35	5	5.5	V
t _{R,VDD}	Supply rise time (0 V to 1.7 V)			60	ms
t _{R,VDDH}	Supply rise time (0 V to 3.7 V)			100	ms
TA	Operating temperature	-40	25	85	°C
TA _{EXT}	Extended operating temperature	85		105	°C
T _J	Junction temperature			110	°C

Important: The on-chip power-on reset circuitry may not function properly for rise times longer than the specified maximum.

3.3 Electronic characteristic

3.3.1 General radio characteristics

Symbol	Description	Min.	Nom.	Max.	Units
f_{OP}	Operating frequencies	2360		2500	MHz
$f_{PLL,CH,SP}$	PLL channel spacing		1		MHz
$f_{\Delta,1M}$	Frequency deviation@1 Mbps		± 170		kHz
$f_{\Delta,BLE,1M}$	Frequency deviation @ BLE 1Mbps		± 250		kHz
$f_{\Delta,2M}$	Frequency deviation @ 2Mbps		± 320		kHz
$f_{\Delta,BLE,2M}$	Frequency deviation@ BLE 2Mbps		± 500		kHz
f_{skBPS}	On-the-air data rate	125		2000	kbps
$f_{chip,IEEE 802.15.4}$	Chip rate in IEEE 802.15.4 mode		2000		kchipAs

3.3.2 Radio current consumption (Transmitter)

Symbol	Description	Min.	Typ.	Max.	Units
$I_{TX,PLUS8dBm,DCDC}$	TX only run current(DCDC,3V) $P_{RF}=+ 8$ dBm		14.2		mA
$I_{TX,PLUS8dBm}$	TX only run current $P_{RF}=+ 8$ dBm		30.4		mA
$I_{TX,PLUS4dBm,DCDC}$	TX only run current(DCDC,3V) $P_{RF}=+ 4$ dBm		9.6		mA
$I_{TX,PLUS4dBm}$	TX only run current $P_{RF}=+ 4$ dBm		20.7		mA
$I_{TX,0dBm,DCDC}$	TX only run current (DC/DC, 3 V) $P_{RF}=0$ dBm		4.9		mA
$I_{TX,0dBm}$	TX only run current $P_{RF}=0$ dBm		10.3		mA
$I_{TX,MINUS4dBm,DCDC}$	TX only run current DCDC,3V $P_{RF}=-4$ dBm		3.8		mA
$I_{TX,MINUS4dBm}$	TX only run current $P_{RF}=-4$ dBm		8.0		mA
$I_{TX,MINUS8dBm,DCDC}$	TX only run current DCDC,3V $P_{RF}=-8$ dBm		3.4		mA
$I_{TX,MINUS8dBm}$	TX only run current $P_{RF}=-8$ dBm		7.1		mA
$I_{TX,MINUS12dBm,DCDC}$	TX only run current DCDC,3V $P_{RF}=-12$ dBm		3.1		mA

$I_{TX,MINUS12dBm}$	TX only run current $P_{RF} = -12$ dBm	6.4	mA
$I_{TX,MINUS16dBm,DCDC}$	TX only run current DCDC,3V $P_{RF} = -16$ dBm	2.9	mA
$I_{TX,MINUS16dBm}$	TX only run current $P_{RF} = -16$ dBm	5.9	mA
$I_{TX,MINUS20dBm,DCDC}$	TX only run current DCDC,3V $P_{RF} = -20$ dBm	2.7	mA
$I_{TX,MINUS20dBm}$	TX only run current $P_{RF} = -20$ dBm	5.5	mA
$I_{TX,MINUS40dBm,DCDC}$	TX only run current DCDC,3V $P_{RF} = -40$ dBm	2.3	mA
$I_{TX,MINUS40dBm}$	TX only run current $P_{RF} = -40$ dBm	4.5	mA
$I_{START,TX,DCDC}$	TX start-up current DCDC,3V $P_{RF} = 4$ dBm	4.3	mA
$I_{START,TX}$	TX start-up current $P_{RF} = 4$ dBm	8.9	mA

3.3.3 Radio current consumption (Receiver)

Symbol	Description	Min	Typ.	Max.	Units
$I_{RX,1M,DCDC}$	RX only run current(DCDC,3V)1Mbps/1Mbps BLE		4.6		mA
$I_{RX,1M}$	RX only run current(LDO,3V)1Mbps/1Mbps BLE		9.6		mA
$I_{RX,2M,DCDC}$	RX only run current(DCDC,3V)2Mbps/2Mbps BLE		5.2		mA
$I_{RX,2M}$	RX only run current(LDO,3V)2Mbps/2Mbps BLE		10.7		mA
$I_{START,RX,1M,DCDC}$	RX start-up current(DCDC,3V)1Mbps/1Mbps BLE		3.4		mA
$I_{START,RX,1M}$	RX start-up current 1Mbps/1Mbps BLE		6.8		mA

3.3.4 Transmitter specification

Symbol	Description	Min	Typ.	Max.	Units
P_{RF}	Maximum output power		8		dBm
P_{RFC}	RF power control range		28		dB
P_{RFCR}	RF power accuracy			±4	dB
$P_{RF1,1}$	1st adjacent channel transmit power 1 MHz(1 Mbps)		-25		dBc
$P_{RF2,1}$	2nd adjacent channel transmit power 2 MHz(1 Mbps)		-54		dBc
$P_{RF1,2}$	1st adjacent channel transmit power 2 MHz(2 Mbps)		-26		dBc
$P_{RF2,2}$	2nd adjacent channel transmit power 4 MHz(2 Mbps)		-54		dBc
E_{vm}	Error Vector Magnitude IEEE 802.15.4		9		%rms
$P_{harm2nd,IEEE 802.15.4}$	2 nd Harmonics in IEEE 802.15.4 mode		-51		dBm
$P_{harm3rd,IEEE 802.15.4}$	3 rd Harmonics in IEEE 802.15.4		-51		dBm

3.3.5 Receiver operation

Symbol	Description	Min	Typ.	Max.	Units
$P_{RX,MAX}$	Maximum received signal strength at <0.1% PER		0		dBm
$P_{SENS,IT,1M}$	Sensitivity, 1 Mbps nRF mode ¹		-93		dBm
$P_{SENS,IT,2M}$	Sensitivity, 2Mbps nRF mode ²		-89		dBm
$P_{SENS,IT,SP,1M,BLE}$	Sensitivity,1 Mbps BLE ideal transmitter,<=37 bytes BER=1E-3 ³		-96		dBm
$P_{SENS,IT,LP,1M,BLE}$	Sensitivity,1 Mbps BLE ideal transmitter,>=128 bytes BER=1E-4 ⁴		-94		dBm
$P_{SENS,IT,SP,2M,BLE}$	Sensitivity, 2 Mbps BLE ideal transmitter, Packet length <=37 bytes		-92		dBm
$P_{SENS,IT,BLE LE125K}$	Sensitivity,125kbps BLE mode		-103		dBm
$P_{SENS,IT,BLE LE500K}$	Sensitivity, 500kbps BLE mode		-98		dBm
$P_{SENSE,IEEE 802.15.4}$	Sensitivity in IEEE 802.15.4 mode		-100		dBm

¹ Typical sensitivity applies when ADDR0 is used for receiver address correlation. When ADDR[1...7] are used for receiver address correlation, the typical sensitivity for this mode is degraded by 3dB.

² Desired signal level at PIN = -67 dBm. One interferer is used, having equal modulation as the desired signal. The input power of the interferer where the sensitivity equals BER = 0.1% is presented.

³ As defined in the Bluetooth Core Specification v4.0 Volume 6: Core System Package (Low Energy Controller Volume)

⁴ Equivalent BER limit < 10E-04

3.3.6 RX selectivity

Symbol	Description	Min	Typ.	Max.	Units
$C/I_{1M,co-channel}$	1Mbps mode, Co-Channel interference		10		dB
$C/I_{1M,-1MHz}$	1 Mbps mode, Adjacent (-1 MHz) interference		-5		dB
$C/I_{1M,+1MHz}$	1 Mbps mode, Adjacent (+1 MHz) interference		-14		dB
$C/I_{1M,-2MHz}$	1 Mbps mode, Adjacent (-2 MHz) interference		-19		dB
$C/I_{1M,+2MHz}$	1 Mbps mode, Adjacent (+2 MHz) interference		-42		dB
$C/I_{1M,-3MHz}$	1 Mbps mode, Adjacent (-3 MHz) interference		-37		dB
$C/I_{1M,+3MHz}$	1 Mbps mode, Adjacent (+3 MHz) interference		-47		dB
$C/I_{1M,\pm 6MHz}$	1 Mbps mode, Adjacent (≥ 6 MHz) interference		-52		dB
$C/I_{1MBLE,co-channel}$	1 Mbps BLE mode, Co-Channel interference		6		dB
$C/I_{1MBLE,-1MHz}$	1 Mbps BLE mode, Adjacent (-1 MHz) interference		-2		dB
$C/I_{1MBLE,+1MHz}$	1 Mbps BLE mode, Adjacent (+1 MHz) interference		-10		dB
$C/I_{1MBLE,-2MHz}$	1 Mbps BLE mode, Adjacent (-2 MHz) interference		-23		dB
$C/I_{1MBLE,+2MHz}$	1 Mbps BLE mode, Adjacent (+2 MHz) interference		-45		dB
$C/I_{1MBLE,>3MHz}$	1 Mbps BLE mode, Adjacent (≥ 3 MHz) interference		-54		dB
$C/I_{1MBLE,image}$	Image frequency Interference		-24		dB
$C/I_{1MBLE,image,1MHz}$	Adjacent (1 MHz) interference to in-band image frequency		-37		dB
$C/I_{2M,co-channel}$	2Mbps mode, Co-Channel interference		10		dB
$C/I_{2M,-2MHz}$	2 Mbps mode, Adjacent (-2 MHz) interference		-4		dB
$C/I_{2M,+2MHz}$	2 Mbps mode, Adjacent (+2 MHz) interference		-16		dB
$C/I_{2M,-4MHz}$	2 Mbps mode, Adjacent (-4 MHz) interference		-19		dB
$C/I_{2M,+4MHz}$	2 Mbps mode, Adjacent (+4 MHz) interference		-46		dB
$C/I_{2M,-6MHz}$	2 Mbps mode, Adjacent (-6 MHz) interference		-41		dB
$C/I_{2M,+6MHz}$	2 Mbps mode, Adjacent (+6 MHz) interference		-48		dB
$C/I_{2M,\geq 12MHz}$	2 Mbps mode, Adjacent (≥ 12 MHz) interference		-52		dB

$C/I_{2\text{MBLE,co-channel}}$	2 Mbps BLE mode, Co-Channel interference	7	dB
$C/I_{2\text{MBLE,-2MHz}}$	2 Mbps BLE mode, Adjacent (-2 MHz) interference	-2	dB
$C/I_{2\text{MBLE,+2MHz}}$	2 Mbps BLE mode, Adjacent (+2 MHz) interference	-12	dB
$C/I_{2\text{MBLE,-4MHz}}$	2 Mbps BLE mode, Adjacent (-4 MHz) interference	-22	dB
$C/I_{2\text{MBLE,+4MHz}}$	2 Mbps BLE mode, Adjacent (+4 MHz) interference	-46	dB
$C/I_{2\text{MBLE,}\geq 6\text{MHz}}$	2 Mbps BLE mode, Adjacent (≥ 6 MHz) interference	-52	dB
$C/I_{2\text{MBLE,image}}$	Image frequency interference	-22	dB
$C/I_{2\text{MBLE,image, 2MHz}}$	Adjacent (2 MHz) interference to in-band image frequency	-37	dB
$C/I_{125\text{k BLE LR, co-channel}}$	125 kbps BLE LR mode, Co-Channel interference	3	dB
$C/I_{125\text{k BLE LR,-1MHz}}$	125 kbps BLE LR mode, Adjacent (-1 MHz) interference	-9	dB
$C/I_{125\text{k BLE LR,+1MHz}}$	125 kbps BLE LR mode, Adjacent (+1 MHz) interference	-16	dB
$C/I_{125\text{k BLE LR,-2MHz}}$	125 kbps BLE LR mode, Adjacent (-2 MHz) interference	-27	dB
$C/I_{125\text{k BLE LR,+2MHz}}$	125 kbps BLE LR mode, Adjacent (+2 MHz) interference	-54	dB
$C/I_{125\text{k BLE LR,>3MHz}}$	125 kbps BLE LR mode, Adjacent (≥ 3 MHz) interference	-60	dB
$C/I_{125\text{k BLE LR,image}}$	Image frequency Interference	-27	dB
$C/I_{\text{IEEE 802.15.4, -5MHz}}$	IEEE 802.15.4 mode, Adjacent (-5 MHz) rejection	-33	dB
$C/I_{\text{IEEE 802.15.4, +5MHz}}$	IEEE 802.15.4 mode, Adjacent (+5 MHz) rejection	-38	dB
$C/I_{\text{IEEE 802.15.4,}\pm 10\text{MHz}}$	IEEE 802.15.4 mode, Alternate (± 10 MHz) rejection	-49	dB

3.3.7 RX intermodulation

Symbol	Description	Min	Typ.	Max.	Units
$P_{\text{IMD,5TH,1M}}$	IMD performance, 1 Mbps, 5th offset channel, packet length ≤ 37 bytes		-34		dBm
$P_{\text{IMD,5TH,1M, BLE}}$	IMD performance, BLE 1 Mbps, 5th offset channel, packet length ≤ 37 bytes		-32		dBm
$P_{\text{IMD,5TH,2M}}$	IMD performance, 2 Mbps, 5th offset channel, packet length ≤ 37 bytes		-33		dBm
$P_{\text{IMD,5TH,2M, BLE}}$	IMD performance, BLE 2 Mbps, 5th offset channel, packet length ≤ 37 bytes		-32		dBm

3.3.8 Radio timing

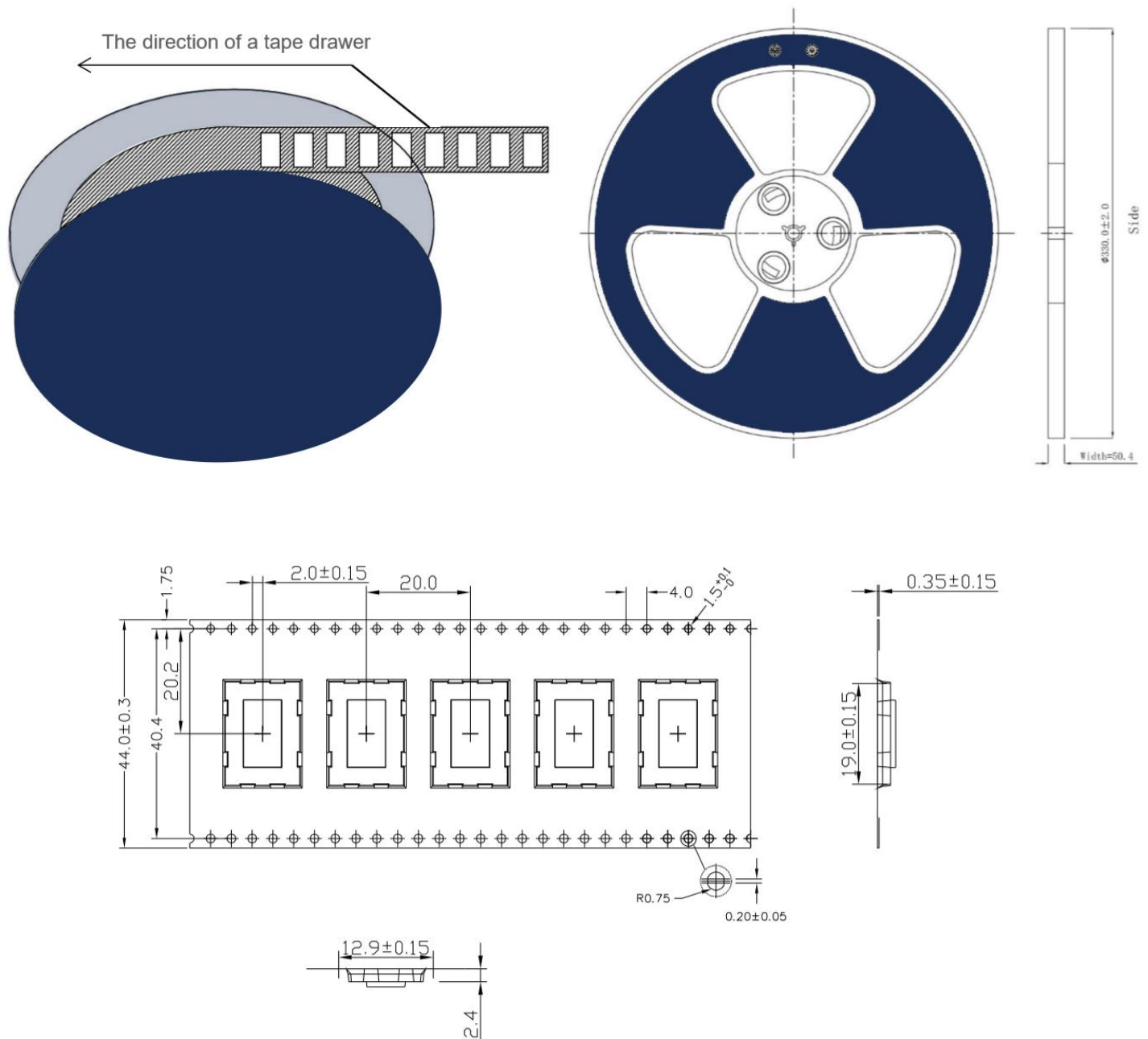
Symbol	Description	Min	Typ.	Max.	Units
$t_{TXEN,BLE,1M}$	Time between TXEN task and READY event after channel FREQUENCY configured	140		140	us
$t_{TXEN,FAST,BLE,1M}$	Time between TXEN task and READY event after channel FREQUENCY configured (Fast Mode)	40		40	us
$t_{TXDIS,BLE,1M}$	When in TX, delay between DISABLE task and DISABLED event for MODE = Nrf_1Mbit and MODE = Ble_1Mbit	6		6	us
$t_{TXDIS,BLE,1M}$	Time between the RXEN task and READY event after channel FREQUENCY configured (1 Mbps BLE)	140		140	us
$T_{rxen,FAST,BLE,1M}$	Time between the RXEN task and READY event after channel FREQUENCY configured (1 Mbps BLE with fast ramp-up)	40		40	us
$t_{RXDIS,BLE,1M}$	When in RX, delay between DISABLE task and DISABLED event for MODE = Nrf_1Mbit and MODE = Ble_1Mbit	0		0	us
$t_{TXDIS,BLE,2M}$	When in TX, delay between DISABLE task and DISABLED event for MODE = Nrf_2Mbit and MODE = Ble_2Mbit	4		4	us
$t_{RXDIS,BLE,2M}$	When in RX, delay between DISABLE task and DISABLED event for MODE = Nrf_2Mbit and MODE = Ble_2Mbit	0		0	us
$t_{TXEN,IEEE 802.15.4}$	Time between TXEN task and READY event after channel FREQUENCY configured (IEEE 802.15.4)	130		130	us
$t_{TXEN,FAST,IEEE 802.15.4}$	Time between TXEN task and READY event after channel FREQUENCY configured (IEEE 802.15.4 with fast ramp-up)	40		40	us
$t_{TXDIS,IEEE 802.15.4}$	When in TX, delay between DISABLE task and DISABLED event (IEEE 802.15.4)	21		21	us
$t_{RXEN,IEEE 802.15.4}$	Time between the RXEN task and READY event after channel FREQUENCY configured (IEEE 802.15.4)	130		130	us
$t_{RXEN,FAST,IEEE 802.15.4}$	Time between the RXEN task and READY event after channel FREQUENCY configured (IEEE 802.15.4 with fast ramp-up)	40		40	us
$t_{RXDIS,IEEE 802.15.4}$	When in RX, delay between DISABLE task and DISABLED event (IEEE 802.15.4)	0.5		0.5	us
$t_{RX-to-TX \text{ turnaround}}$	Maximum TX-to-RX or RX-to-TX turnaround time in IEEE 802.15.4 mode		40		us

3.3.9 Received signal strength indicator (RSSI) specifications

Symbol	Description	Min	Typ.	Max.	Units
RSSI _{ACC}	RSSI accuracy		±2		dB
RSSI _{RESOLUTION}	RSSI resolution		1		dB
RSSI _{PERIOD}	RSSI sampling time from RSSI_START task		0.25		us
RSSI _{SETTLE}	RSSI settling time after signal level change		15		us

5 Package Information

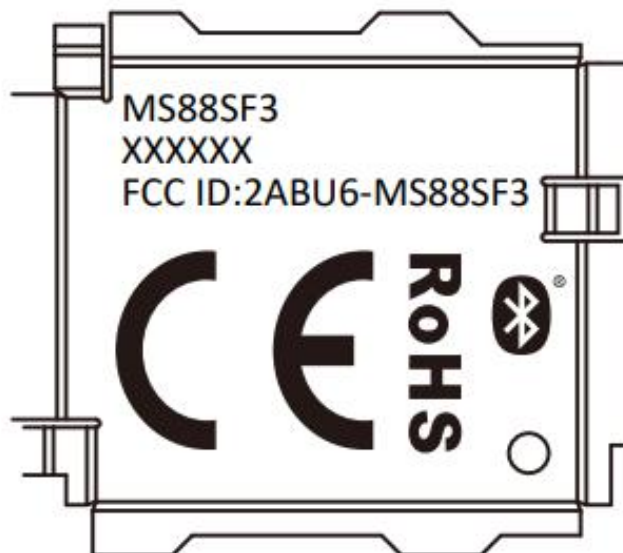
5.1 Package dimension



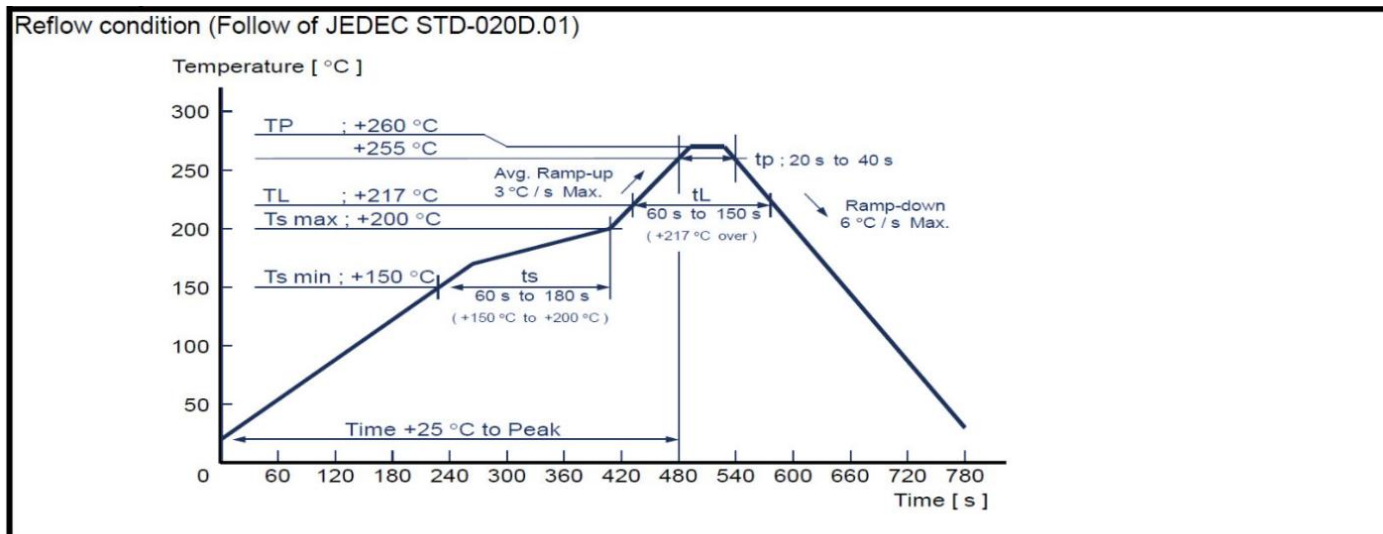
Details of Package Dimension:

Details	Reel-MS88SF3
Quantity(module)	850PCS
Tape Weight	760g
Single module Weight	1.1g
Gross Weight	1200g
Dimension	W: 44mm T: 0.35mm

5.2 Mark on metal shield



6 Reflow and Soldering



Profile Feature	Sn-Pb Assembly	Pb-Free Assembly
Solder Paste	Sn63/Pb37	Sn96.5/Ag3/Cu0.5
Preheat Temperature min (T _{smin})	100°C	150°C
Preheat Temperature max (T _{smax})	150°C	200°C
Preheat Time (T _{smin} to T _{smax})(t _s)	60-120 sec	60-120 sec
Average ramp-up rate (T _{smax} to T _p)	3°C/second max	3°C/second max
Liquidous Temperature (TL)	183°C	217°C
Time (t _L)Maintained Above (TL)	60-90 sec	30-90 sec
Peak Temperature (T _p)	220-235°C	230-250°C
Average ramp-down rate (T _p to T _{smax})	6°C/second max	6°C/second max
Time 25°C to peak temperature	6 minutes max	8 minutes max

Important:

- When SMT involves double-sided patch, it is recommended that the module surface be reflowed only once.
- For module SMT, it is recommended to make a partial stepped stencil with a thickness of 0.2mm, and the stencil hole should be extended by 0.8mm size.
- After opening the package, it should be stored in vacuum environment. Module should not be exposed to the air for a long time to prevent moisture and pad oxidation. If there is an interval of 7 to 30 days during SMT process, it is recommended to bake it with reel at 65-70 degrees for 24 hours before using for SMT again.

7 Certification

BQB QDID: 150211

FCC ID: 2ABU6-MS88SF3

CE,RoHS & Reach certified

7.1 CE Certification

MS88SF3 module is being tested and is expected to be compliant against the EU-Radio Equipment standards. OEM integrator should consult with qualified test house to verify all regulatory requirements have been met for their complete device.

7.2 FCC Certification

MS88SF3 module is being tested and is expected to be compliant against the Federal Communications Commission standards.

As for the OEM integration:

Only OEM integrator have right to intend this device under the following conditions:

Any other transmitter or antenna must not be co-located with the antenna and transmitter. The module shall be only used with the integral antenna(s) that has been originally tested and certified with this module.

As long as the two conditions below are met, further transmitter testing will not be required.

(1) This device may not cause harmful interference.

(2) This device must accept any interference received, including interference that may cause undesired operation.

However, the OEM integrator shall test their end-product for any additional compliance requirements with this module installed (for example, digital device emission, PC peripheral requirements, etc.).

If these conditions cannot be met (for example certain laptop configuration or co-location with another transmitter), then the FCC authorization for this module in combination with the host equipment is no longer considered valid and the final product shall not use the FCC ID of the module. In these circumstances, the OEM integrator shall be re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

The OEM shall be verifying end product compliance with FCC Part 15, sub-part B limits for unintentional radiators through an accredited test facility.

7.3 Full Bluetooth Declaration ID

Minewsemi technologies meet the Bluetooth specification maintained by Bluetooth SIG, and all the product produced by Minewsemi is properly tested and comply with the Bluetooth license agreements.

Minewsemi is one of the associate member of Bluetooth SIG. The requirement of listing products by companies is become the members of the SIG and also pay the listed fees for each product required.

Please Kindly check the below Link to know more info:

<https://www.bluetooth.com/develop-with-bluetooth/qualification-listing>.

The Minewsemi Bluetooth Low Energy modules based on Nordic Semiconductor SoCs are listed as a “End product”.

7.4 Environmental

7.4.1 RoHs

MS88SF3 modules are in compliance with Directive 2011/65/EU, 2015/863/EU of the European Parliament and the Council on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

7.4.2 Reach

MS88SF3 modules listed below do not contain the 191 SVHC (Substance of Very High Concern), as defined by Directive EC/1907/2006 Article according to REACHAnnex XVII.

8 Notes & Cautions

We cannot assure that the specification has no errors and omission even though this specification is under collate and check strictly.

This specification is under the protection of laws and regulations of copyright, please do not copy and duplicate at any form, or do not transmit part or full of this specification in any wire and wireless network in any form, or do not edit or translate to any other format, word, code, etc.

8.1 Design notes

- It is critical to following the recommendations of this document to ensure the module meets the specifications.
- The module should be placed at the edge of the circuit board as far as possible to keep away from other circuits.
- Antenna should be kept away from other circuits. It can prevent low radiation efficiency and the normal use of other circuits from being affected.
- The landing of components should be appropriate and that is better for reducing the parasitic inductance.
- Please refuse to supply voltage that is not within the range of specification.
- Please make sure the module or its surface may not suffer from the physical shock or extreme stress.

8.2 Layout notes

To make sure wireless performance is at its best condition, please layout the MS88SF3 module on the carrier board as below instructions and picture.

a) Placement of the antenna

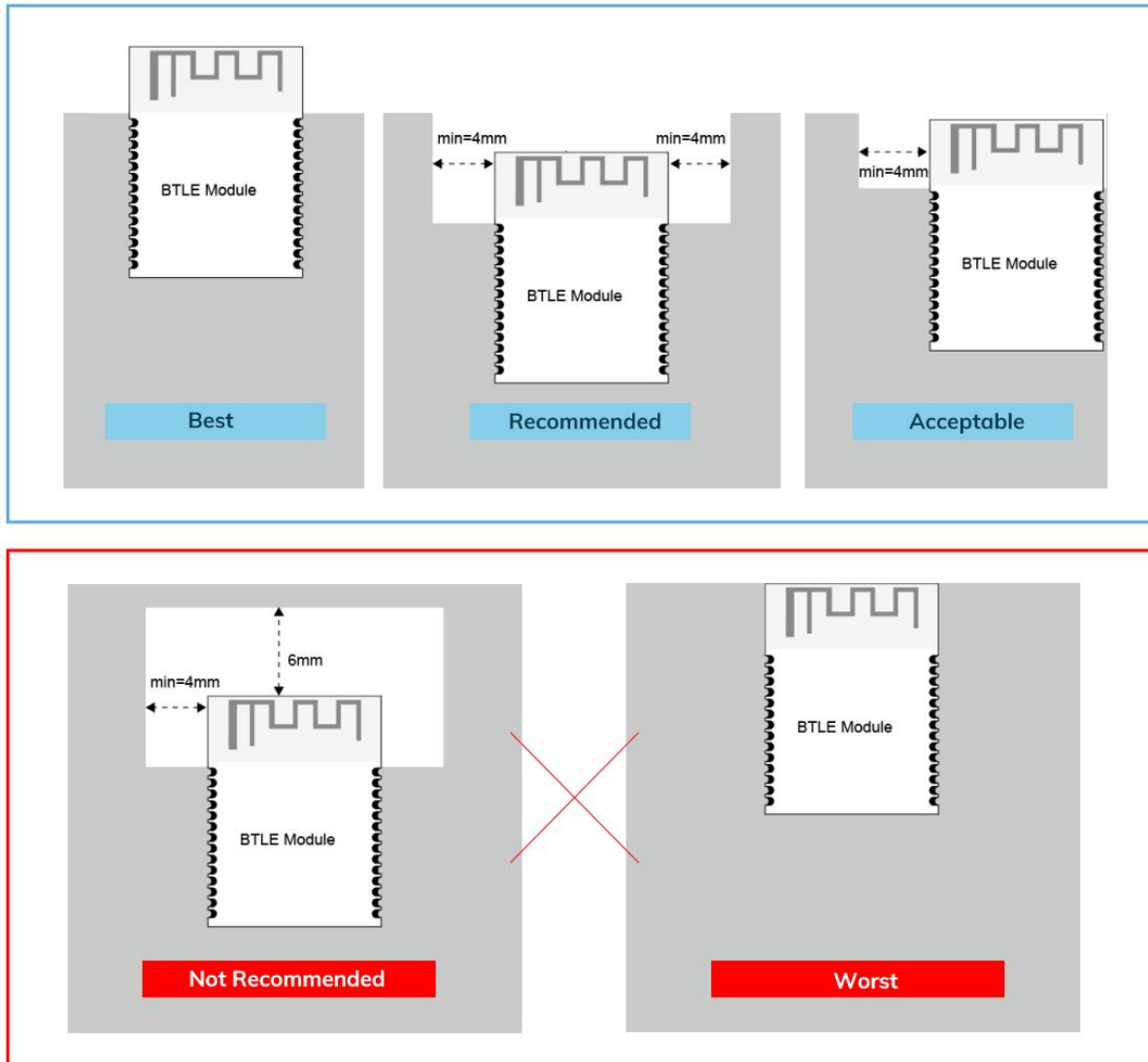
The antenna area of module shall lay clearance completely and should not be blocked by the metal. Otherwise it will have effect on antenna performance (As the picture indicated below).

b) Placement of top-layer

The placement of top-layer in carrier board shall be lay copper completely to reduce the signal line in carrier board or other interference.

c) Clearance

The upper and below area of antenna (including the case) shall have 4mm or more than 4mm clearance to reduce the influences for antenna.



*The Grey area above is Carrier board.

8.3 Installation and soldering

Please do not lay copper under the module antenna. It can prevent the influence of signal radiation and the transmission distance from being affected.

8.4 Handling and storage

- Due to the fact that CMOS components are included in the module, it is better to eliminate static electricity at any methods when transporting or working with the module. Moreover, it is strongly recommended adding anti-ESD components to circuit design to hinder damage from real-life ESD events. Anti-ESD methods can be also used in mechanical design.



- b) Please store the modules within -40°C to $+125^{\circ}\text{C}$ before and after installation and make sure the modules is away from the direct sunlight exposure for a long duration. Modules should be far away from humid and salty air conditions, and any corrosive gasses or substances.
- c) Please not to wash the module. No-Clean Paste is used in production. The metal shield may be oxidized by the washing process and may lead to chemistry reaction with No-Clean Paste. If modules goes through the washing process, functions of the module may not guaranteed.
- d) After opening the package, it should be stored in vacuum environment. Module should not be exposed to the air for a long time to prevent moisture and pad oxidation. If there is an interval of 7 to 30 days during SMT process,

8.5 Life support applications

- a) The module is not design for life support device or system and not allowed to be used in destructive devices or system in any direct, or indirect ways. Minewsemi is not responsible for compensation of any losses when applying modules under such application as described above.
- b) MinewSemi shall not responsible for the customer's products or application.

9 Disclaimer

The factory has passed the ISO9001 quality management system, ISO14001 environmental management system and OAHS18001 occupational health and safety assessment . Each product has been rigorously tested (transmission power test, sensitivity test, power consumption test, stability test, aging test, etc.).

* NOTICES:

- The Bluetooth trade mark is owned by the Bluetooth SIG Inc. USA.
- All other trademarks listed herein are owned by their respective owners.
- All specifications are subject to change without notice.
- Please do not use this specification for produce, sell or illegal purpose without MinewSemi's authorization.
- MinewSemi have right to interpret all the items above.

Revision History

Version	Date	Notes	Contributor (s)	Person of Approve
1.0	2022-03-01	First edition	Eddie	Coral

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